

N- and P-Channel Enhancement-Mode Dual MOSFET

Features

- ▶ Low threshold
- ▶ Low on resistance
- ▶ Low input capacitance
- ▶ Fast switching speeds
- ▶ Freedom from secondary breakdown
- ▶ Low input and output leakage
- ▶ Independent, electrically isolated N- and P-channels

Applications

- ▶ Medical ultrasound transmitters
- ▶ High voltage pulsers
- ▶ Amplifiers
- ▶ Buffers
- ▶ Piezoelectric transducer drivers
- ▶ General purpose line drivers
- ▶ Logic level interface

General Description

The Supertex TC2320TG consists of a high voltage, low threshold N- and P-channel MOSFET in an SO-8 package. These low threshold enhancement-mode (normally-off) transistors utilize an advanced vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Ordering Information

Device	Package Options	BV_{DSS}/BV_{DGS} (V)		$R_{DS(ON)}$ (max) (Ω)	
		N-Channel	P-Channel	N-Channel	P-Channel
TC2320	TC2320TG-G	200	-200	7.0	12

-G indicates package is RoHS compliant ('Green')



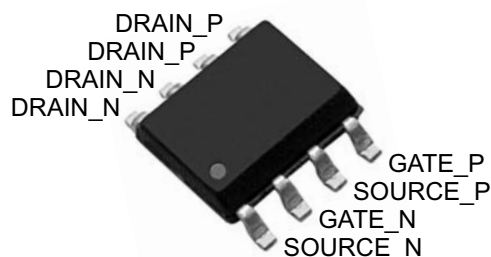
Absolute Maximum Ratings

Parameter	Value
Drain to source voltage	BV_{DSS}
Drain to gate voltage	BV_{DGS}
Gate to source voltage	$\pm 20V$
Operating and storage temperature	$-55^{\circ}C$ to $+150^{\circ}C$
Soldering temperature*	$+300^{\circ}C$

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

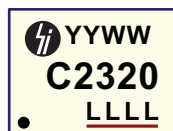
* Distance of 1.6mm from case for 10 seconds.

Pin Configuration



8-Lead SOIC (TG)

Product Marking



YY = Year Sealed
WW = Week Sealed
L = Lot Number
_____ = "Green" Packaging

8-Lead SOIC (TG)

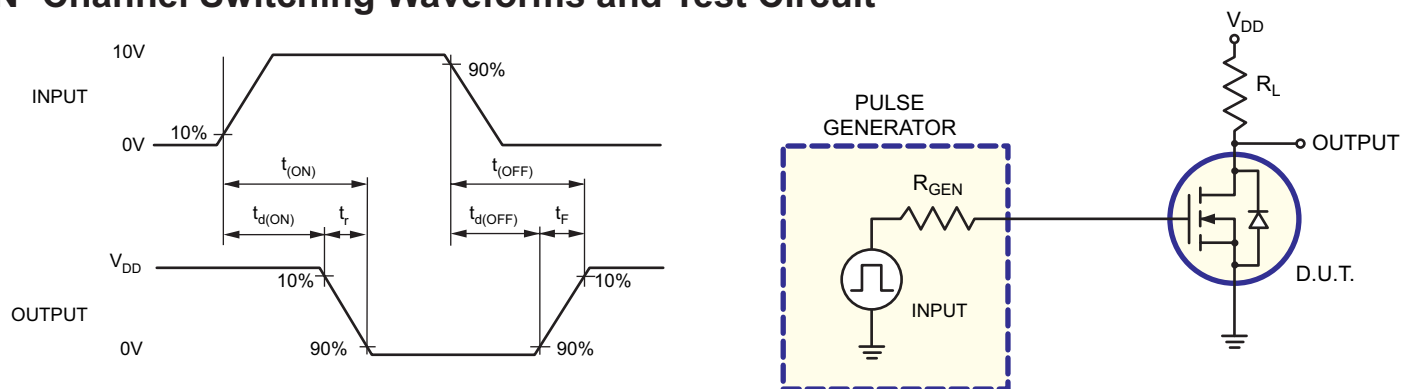
N-Channel Electrical Characteristics (@ 25°C unless otherwise specified)

Symbol	Parameter	Min	Typ	Max	Units	Conditions
BV_{DSS}	Drain-to-source breakdown voltage	200	-	-	V	$V_{GS} = 0V, I_D = 100\mu A$
$V_{GS(th)}$	Gate threshold voltage	0.6	-	2.0	V	$V_{GS} = V_{DS}, I_D = 1.0mA$
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	-	-4.5	mV/°C	$V_{GS} = V_{DS}, I_D = 1.0mA$
I_{GSS}	Gate body leakage	-	-	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
I_{DSS}	Zero gate voltage drain current	-	-	1.0	μA	$V_{GS} = 0V, V_{DS} = 100V$
		-	-	10.0	μA	$V_{GS} = 0V, V_{DS} = \text{Max rating}$
		-	-	1.0	mA	$V_{GS} = 0V, T_A = 125^\circ C, V_{DS} = 0.8 \text{ Max Rating}$
$I_{D(ON)}$	ON-state drain current	0.6	-	-	A	$V_{GS} = 4.5V, V_{DS} = 25V$
		1.2	-	-		$V_{GS} = 10V, V_{DS} = 25V$
$R_{DS(ON)}$	Static drain-to-source ON-state resistance	-	-	8.0	Ω	$V_{GS} = 4.5V, I_D = 150mA$
		-	-	7.0		$V_{GS} = 10V, I_D = 1.0A$
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	150	-	1.0	%/°C	$V_{GS} = 4.5V, I_D = 150mA$
G_{FS}	Forward transconductance	-	-	-	mmho	$V_{DS} = 25V, I_D = 200mA$
C_{ISS}	Input capacitance	-	-	110	pF	$V_{GS} = 0V, V_{DS} = 25V, f = 1.0MHz$
C_{OSS}	Common source output capacitance	-	-	60		
C_{RSS}	Reverse transfer capacitance	-	-	23		
$t_{d(ON)}$	Turn-ON delay time	-	-	20	ns	$V_{DD} = 25V, I_D = 150mA, R_{GEN} = 25\Omega$
t_r	Rise time	-	-	15		
$t_{d(OFF)}$	Turn-OFF delay time	-	-	25		
t_f	Fall time	-	-	25		
V_{SD}	Diode forward voltage drop	-	-	1.8	V	$V_{GS} = 0V, I_{SD} = 200mA$
t_{rr}	Reverse recovery time	-	300	-	ns	$V_{GS} = 0V, I_{SD} = 200mA$

Notes:

- 1.All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300 μs pulse, 2% duty cycle.)
- 2.All A.C. parameters sample tested.

N-Channel Switching Waveforms and Test Circuit



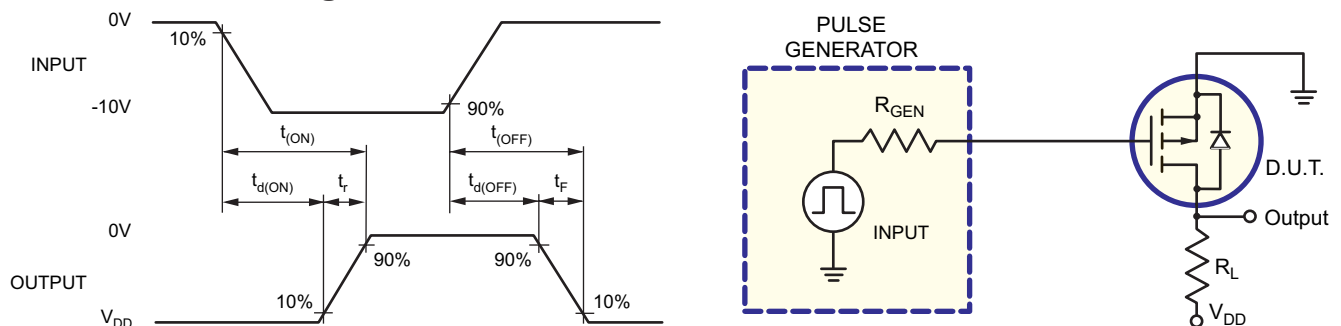
P-Channel Electrical Characteristics (@ 25°C unless otherwise specified)

Symbol	Parameter	Min	Typ	Max	Units	Conditions
BV_{DSS}	Drain-to-source breakdown voltage	-200	-	-	V	$V_{GS} = 0V, I_D = -2.0mA$
$V_{GS(th)}$	Gate threshold voltage	-1.0	-	-2.4	V	$V_{GS} = V_{DS}, I_D = -1.0mA$
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	-	4.5	mV/°C	$V_{GS} = V_{DS}, I_D = -1.0mA$
I_{GSS}	Gate body leakage	-	-	-100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
I_{DSS}	Zero gate voltage drain current	-	-	-10	μA	$V_{GS} = 0V, V_{DS} = \text{Max rating}$
		-	-	-1.0	mA	$V_{GS} = 0V, T_A = 125^\circ C, V_{DS} = 0.8 \text{ Max Rating}$
$I_{D(ON)}$	ON-state drain current	-0.25	-0.7	-	A	$V_{GS} = -4.5V, V_{DS} = -25V$
		-0.75	-2.1	-		$V_{GS} = -10V, V_{DS} = -25V$
$R_{DS(ON)}$	Static drain-to-source ON-state resistance	-	10	15	Ω	$V_{GS} = -4.5V, I_D = -100mA$
		-	8.0	12		$V_{GS} = -10V, I_D = -200mA$
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	100	-	1.7	%/°C	$V_{GS} = -10V, I_D = -200mA$
G_{FS}	Forward transconductance	-	250	-	mmho	$V_{DS} = -25V, I_D = -200mA$
C_{ISS}	Input capacitance	-	75	125	pF	$V_{GS} = 0V, V_{DS} = -25V, f = 1.0MHz$
C_{OSS}	Common source output capacitance	-	20	85		
C_{RSS}	Reverse transfer capacitance	-	10	35		
$t_{d(ON)}$	Turn-ON delay time	-	-	10	ns	---
t_r	Rise time	-	-	15		
$t_{d(OFF)}$	Turn-OFF delay time	-	-	20		
t_f	Fall time	-	-	15		
V_{SD}	Diode forward voltage drop	-	-	-1.8	V	$V_{GS} = 0V, I_{SD} = -0.5A$
t_{rr}	Reverse recovery time	-	300	-	ns	$V_{GS} = 0V, I_{SD} = -0.5A$

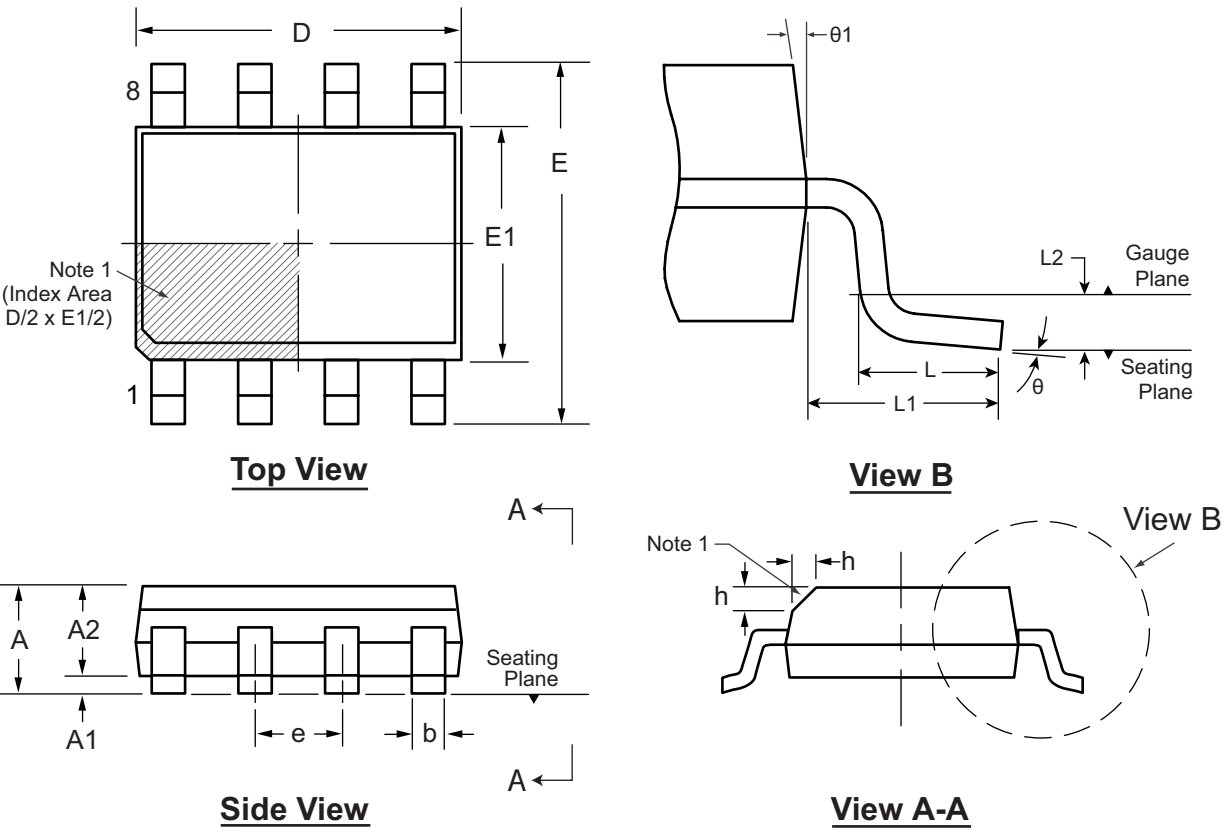
Notes:

1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300 μs pulse, 2% duty cycle.)
2. All A.C. parameters sample tested.

P- Channel Switching Waveforms and Test Circuit



8-Lead SOIC (Narrow Body) Package Outline (TG) 4.9x3.9mm body, 1.75mm height (max), 1.27mm pitch



Note 1:
This chamfer feature is optional. If it is not present, then a Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier may be either a mold, or an embedded metal or marked feature.

Symbol		A	A1	A2	b	D	E	E1	e	h	L	L1	L2	θ	θ1
Dimension (mm)	MIN	1.35	0.10	1.25	0.31	4.80	5.80	3.80	1.27 BSC	0.25	0.40	1.04 REF	0.25 BSC	0°	5°
	NOM	-	-	-	-	4.90	6.00	3.90		-	-			-	-
	MAX	1.75	0.25	1.50	0.51	5.00	6.20	4.00		0.50	1.27			8°	15°

JEDEC Registration MS-012, Variation AA, Issue E, Sept. 2005.
Drawings not to scale.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <http://www.supertex.com/packaging.html>.)

Supertex inc. does not recommend the use of its products in life support applications, and will not knowingly sell its products for use in such applications, unless it receives an adequate "product liability indemnification insurance agreement". **Supertex** does not assume responsibility for use of devices described and limits its liability to the replacement of the devices determined defective due to workmanship. No responsibility is assumed for possible omissions or inaccuracies. Circuitry and specifications are subject to change without notice. For the latest product specifications, refer to the **Supertex** website: <http://www.supertex.com>.